



## Product Information Sheet EPO-TEK® EV2118-2

**Date:** September 2017  
**Rev:** VI  
**No. of Components:** Two  
**Mix Ratio by Weight:** 1 : 1  
**Specific Gravity:** Part A: 2.53      Part B: 3.33  
**Pot Life:** 3 Days  
**Shelf Life- Bulk:** One year at room temperature

**Recommended Cure: 150°C / 1 Hour**

**Minimum Alternative Cure(s):**  
*May not achieve performance properties listed below*  
150°C / 10 Minutes  
120°C / 15 Minutes  
100°C / 1 Hour

### NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

**Product Description:** A silver-filled, electrically conductive epoxy designed for semiconductor and electronic assembly.

**Typical Properties:** Cure condition: varies as required      Different batches, conditions & applications yield differing results.

Data below is not guaranteed. To be used as a guide only, not as a specification. \* denotes test on lot acceptance basis

### **PHYSICAL PROPERTIES:**

|                                  |                      |  |
|----------------------------------|----------------------|--|
| * Color (before cure):           | Part A: Shiny silver | Part B: Shiny silver   |
| * Consistency:                   | Smooth paste         |  |
| * Viscosity (23°C) @ 100 rpm:    | 1,500 - 3,000        | cPs  |
| Thixotropic Index:               | 4.4                  |  |
| * Glass Transition Temp:         | ≥ 40                 | °C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -40-200°C @20°C/Min) |
| Shore A Hardness:                | 55                   |  |
| Lap Shear @ 23°C:                | 428                  | psi  |
| Die Shear @ 23°C:                | ≥ 5                  | Kg    1,778 psi  |
| Degradation Temp:                | 325                  | °C   |
| Weight Loss:                     |                      |  |
|                                  | @ 200°C:             | 0.61 %   |
|                                  | @ 250°C:             | 0.84 %   |
|                                  | @ 300°C:             | 1.58 %   |
| Suggested Operating Temperature: | < 250                | °C (Intermittent)  |
| Storage Modulus:                 | 130,977              | psi  |
| * Particle Size:                 | ≤ 20                 | microns  |

### **ELECTRICAL AND THERMAL PROPERTIES:**

|                              |          |        |
|------------------------------|----------|--------|
| Thermal Conductivity:        | 4.0      | W/mK   |
| * Volume Resistivity @ 23°C: | ≤ 0.0005 | Ohm-cm |

**This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.**

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